



Product Change Notification

Change Notification #: 115593 - 00
Change Title: Select Intel® GEMINAX™ A8MAX PEF55208 Chipset,
Intel® GEMINAX™ A8PMAX PEF55218 Chipset,
Intel® GEMINAX™ A8PXXS PEF66218 Chipset,
Intel® GEMINAX™ D8MAX PEF55008 Chipset,
Intel® GEMINAX™ D16PRO PEF55016 Chipset,
Intel® GEMINAX™ D16XXS PEF66016 Chipset,
Intel® GEMINAX™ D32XXS PEF66032 Chipset,
Intel® GEMINAX™ L2MAX PEF55602 Chipset
PCN 115592-00, Product Discontinuance,
Date of Publication: June 19, 2017

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins:	June 19, 2017
Last Product Discontinuance Order Date:	January 19, 2018
Last Product Discontinuance Shipment Date:	July 19, 2018

Description of Change to the Customer:

Select Intel® GEMINAX™ A8MAX PEF55208 Chipset MM#946297, Intel® GEMINAX™ D32XXS PEF66032 Chipset MM#946561, Intel® GEMINAX™ L2MAX PEF55602 Chipset MM#946930, Intel® GEMINAX™ A8PMAX PEF55218 Chipset MM#946937, Intel® GEMINAX™ D8MAX PEF55008 Chipset MM#947004, Intel® GEMINAX™ A8PXXS PEF66218 Chipset MM#946939, Intel® GEMINAX™ L2MAX PEF55602 Chipset MM#946947, Intel® GEMINAX™ L2MAX PEF55602 Chipset MM#946952, Intel® GEMINAX™ D16PRO PEF55016 Chipset MM#947006, Intel® GEMINAX™ D16XXS PEF66016 Chipset MM#947007, will end of life

Customer Impact of Change and Recommended Action:

Customers should place their Last Time Orders by January 19, 2018 and delivery of all orders must be taken no later than July 19, 2018.

Please use the recommended replacement skus as shows on the Products Affected/Intel Ordering Codes table below:

- Intel® VINAX™ A8 PEF88208 PEF88208ELV3X 946778
- Intel® VINAX™ D PEF88300 PEF88300ELA23 946842
- Intel® VINAX™ L2 PEF88602 PEF88602VV3X 946954

Milestone dates are estimates and subject to change based on business and operations conditions.

Please contact your local Intel Field Sales Representative if you have and further questions about this End of Life notice.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#	Recommended Replacement Product Code	Recommended Replacement MM#
Intel® GEMINAX™ A8MAX PEF55208 Chipset	PEF55208EV21	946297	PEF88208ELV3X	946778
Intel® GEMINAX™ D32XXS PEF66032 Chipset	PEF66032E	946561	PEF88300ELA23	946842
Intel® GEMINAX™ L2MAX PEF55602 Chipset	PEF55602HLV21	946930	PEF88602VV3X	946954
Intel® GEMINAX™ A8PMAX PEF55218 Chipset	PEF55218EV21	946937	PEF88208ELV3X	946778
Intel® GEMINAX™ A8PXXS PEF66218 Chipset	PEF66218E	946939	PEF88208ELV3X	946778
Intel® GEMINAX™ L2MAX PEF55602 Chipset	PEF55602VV21	946947	PEF88602VV3X	946954
Intel® GEMINAX™ L2MAX PEF55602 Chipset	PEF55602VV11	946952	PEF88602VV3X	946954
Intel® GEMINAX™ D8MAX PEF55008 Chipset	PEF55008HLV21	947004	PEF88300ELA23	946842
Intel® GEMINAX™ D16PRO PEF55016 Chipset	PEF55016EV21	947006	PEF88300ELA23	946842
Intel® GEMINAX™ D16XXS PEF66016 Chipset	PEF66016E	947007	PEF88300ELA23	946842

PCN Revision History:

Date of Revision:

June 19, 2017

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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